

/ Descriptions

N 沟道 TO-220 封装 MOSFET

N-Channel MOSFET in a TO-220 Plastic Package.

/ Features

$V_{DS}=200V$ $I_D=18A$ $V_{GS}=\pm 20V$

$R_{DS(on)}@10V \leq 170m\Omega$ (Type.115m Ω)

$R_{DS(on)}@6V \leq 200m\Omega$ (Type.130m Ω)

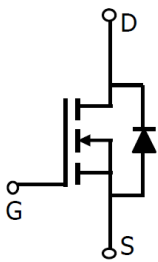
高频产品.

/ Applications

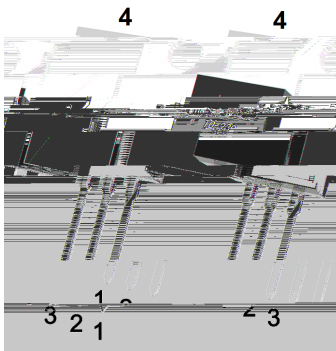
网络,负载开关,LED应用.

Networking, Load Switch, LED applications.

/ Equivalent Circuit



/ Pinning



PIN1 栅极

PIN 2 漏极

PIN 3 源极

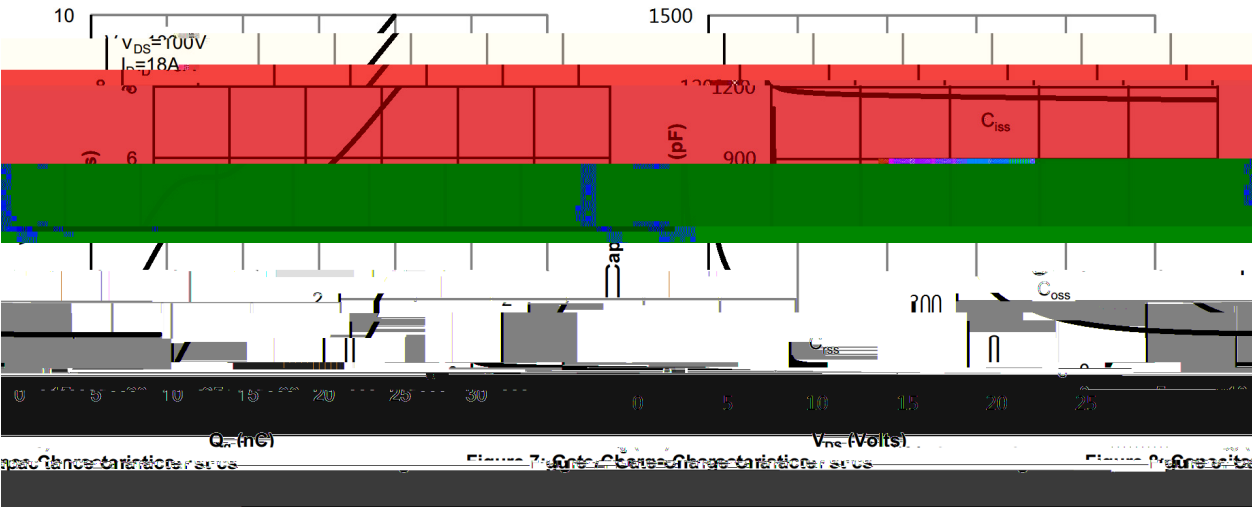
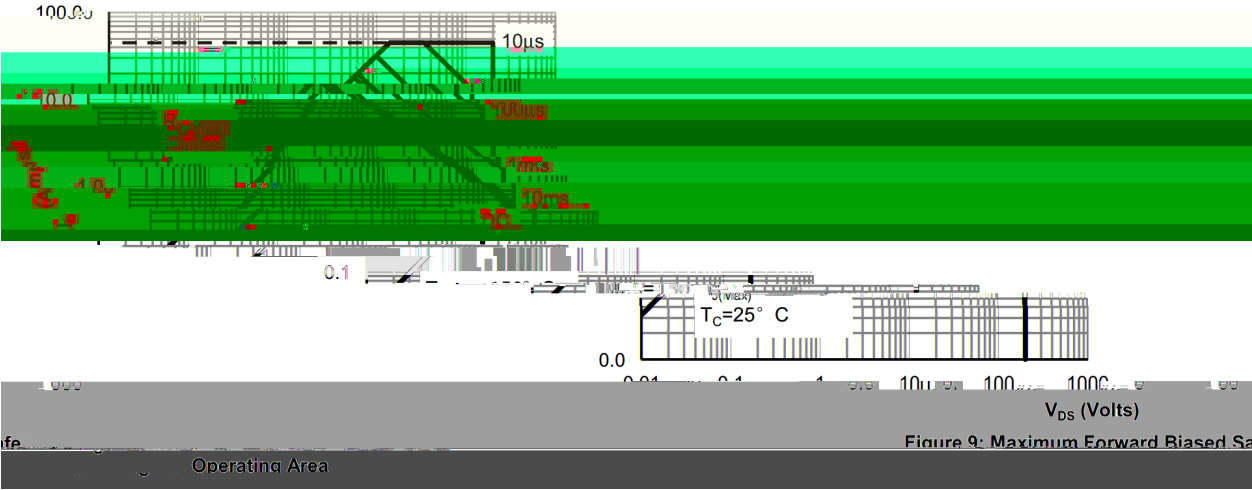
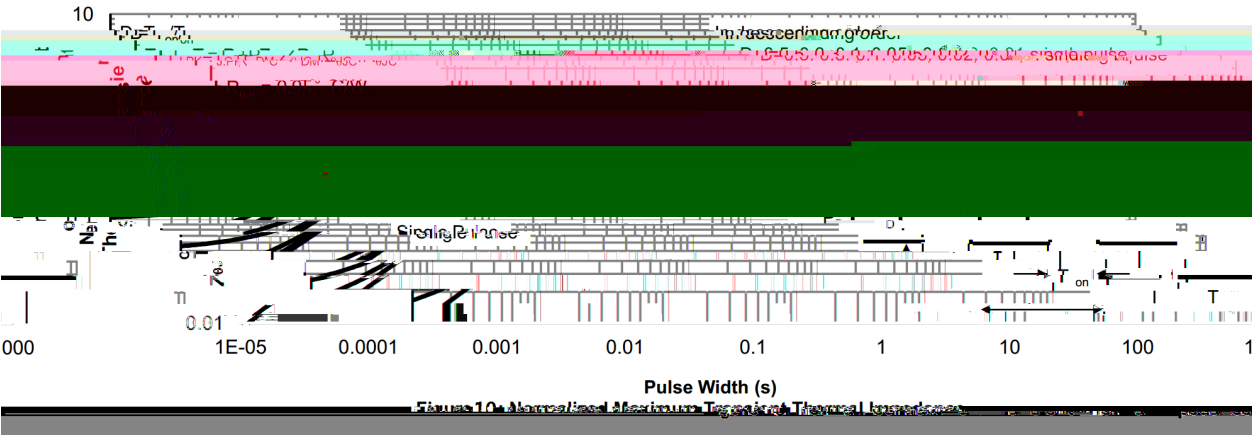
/ Marking

见 marking

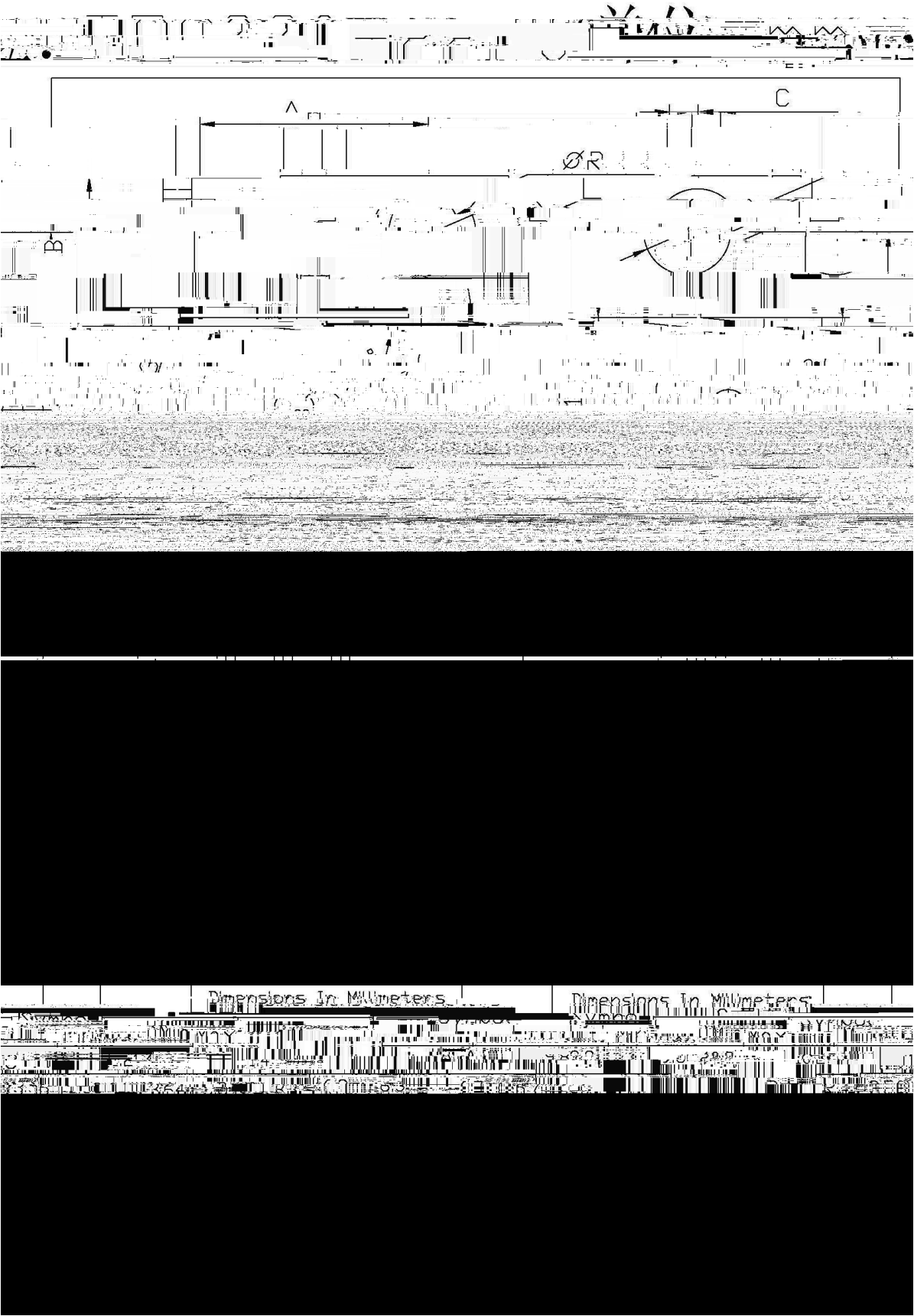
See Marking Instructions.

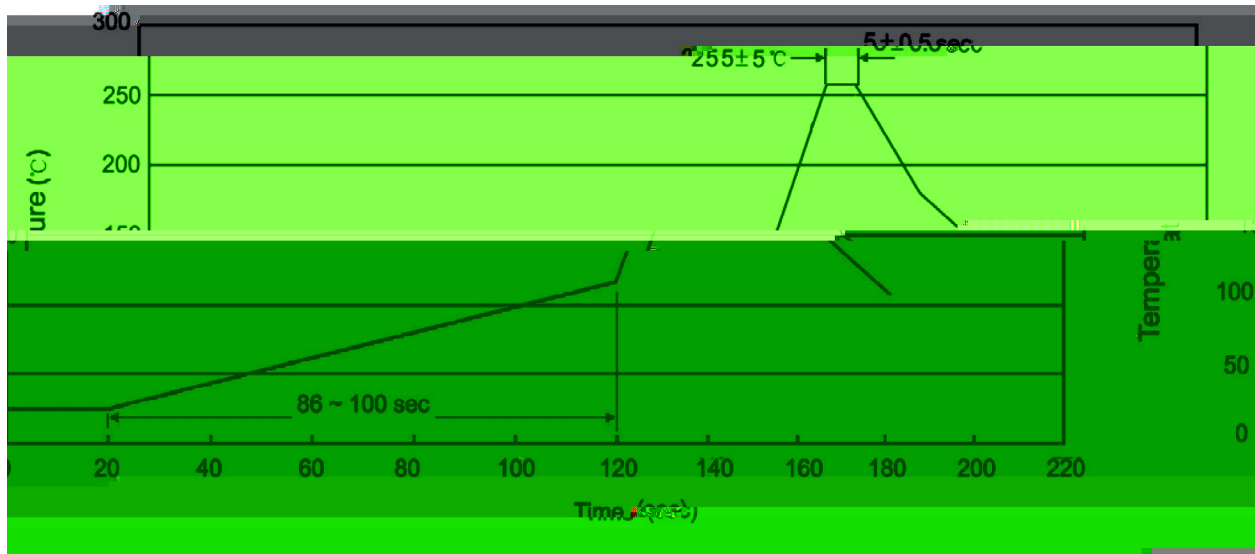
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V$ $V_{DS}=75V$ $R_{GEN}=3F$		11.7		ns
Turn-On Rise Time	t_r			3.5		

/ Electrical Characteristic Curve



/ Package Dimensions



() / Temperature Profile for Dip Soldering(Pb-Free)


说明

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 255±5℃, 持续时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.
2. Peak Temp.: 255±5℃, Duration: 5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度: 270±5℃ 时间: 10±1 sec. Temp.: 270±5 Time: 10±1 sec

/ Packaging SPEC.

包装形式 / BULK